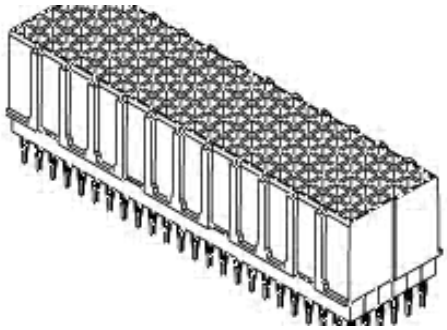
molex



Part Number : 737803254
Product Description : HDM Board-to-Board Daughtercard Receptacle, Vertical, Signal Module, 144 Circuits, Mounted Height 14.00mm, Pin Length 3.50mm, Press-Fit
Series Number : 73780
Status : Active
Product Category : Backplane Connectors

Documents and Resources

Drawings

737803254_sd.pdf

3D Models and Design Files

STEP AP242

SOLIDWORKS

Creo

Specifications

AS-73670-9998-001.pdf

PS-73780-999-001.pdf

Product Environment Compliance

Compliance

GADSL/IMDS	Not Relevant
China RoHS	per SJ/T 11365-2006
EU ELV	Not Relevant
Low-Halogen Status	Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2025)7771-DC (04 Feb 2026)
EU RoHS	Compliant per EU 2015/863

Compliance Statements

- EU RoHS

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- REACH SVHC
- Low-Halogen

Industry Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

Substances of Interest

- PFAS

EU RoHS Certificate of Compliance

Additional Product Compliance Information

Part Details

General

Status	Active
Category	Backplane Connectors
Series	73780
Description	HDM Board-to-Board Daughtercard Receptacle, Vertical, Signal Module, 144 Circuits, Mounted Height 14.00mm, Pin Length 3.50mm, Press-Fit
Application	Daughtercard, Mezzanine
Comments	Press-Fit Tail
Component Type	PCB Receptacle
Product Name	HDM
UPC	800756571355

Agency

UL	E29179

Electrical

Current - Maximum per Contact	15.0A, 1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75

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Shielded	No
Voltage - Maximum	250V AC

Physical

Circuits (Loaded)	144
Circuits (maximum)	144
Color - Resin	Black
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	No
Keying to Mating Part	No
Material - Metal	Copper-Nickel-Tin
Material - Plating Mating	Gold
Material - Plating Termination	Tin-Lead
Material - Resin	High Temperature Thermoplastic
Net Weight	14.734/g
Number of Columns	24
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
Packaging Type	Tube
PCB Locator	No
PCB Retention	No
PCB Thickness - Recommended	1.60mm
PC Tail Length	3.50mm
Pitch - Mating Interface	2.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	0.889µm
Polarized to PCB	No
Stackable	Yes
Temperature Range - Operating	-55° to +105°C
Termination Interface Style	Through Hole - Compliant Pin

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Solder Process Data

Lead-Free Process Capability	N/A

Mates With / Use With

Mates with Part(s)

Description	Part Number
HDM Vertical Backplane Headers	73642
HDM Vertical Backplane Headers	73643
HDM Vertical Backplane Headers	73644
HDM Vertical Backplane Headers	73942
HDM Vertical Backplane Headers	73944
HDM Vertical Stacking Headers	73769
HDM Vertical Stacking Headers	73782
HDM Vertical Stacking Headers	73771

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